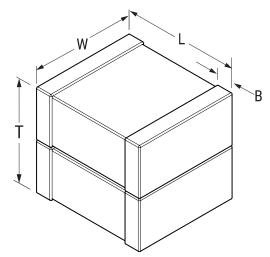


CKC21C204KCGLCTU

KONNEKT KC-LINK Comm COG, Ceramic, 0.2 uF, 10%, 500 VDC, COG, 2-Chip Standard Orientation.



Click here for the 3D model.

| Dimensions | |
|------------|-----------------|
| L | 5.7mm +/-0.4mm |
| W | 5mm +/-0.4mm |
| Т | 5mm +/-0.4mm |
| В | 0.6mm +/-0.35mm |
| | |

| Packaging Specifications | |
|--------------------------|------------|
| Packaging | T&R, 180mm |
| Packaging Quantity | 300 |

| General Information | |
|--------------------------|---|
| Series | KONNEKT KC-LINK Comm COG |
| Style | KONNEKT |
| Description | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features | Ultra-Stable, Low Loss |
| RoHS | Yes |
| Termination | Tin |
| AEC-Q200 | No |
| Typical Component Weight | 600 mg |
| Notes | 2-Chip Standard Orientation. |
| Chip Size | 2220-2 |
| MSL | 1 |

| Specifications | |
|--|------------------------|
| Capacitance | 0.2 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 500 VDC |
| Dielectric Withstanding Voltage | 750 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 5 GOhms |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.